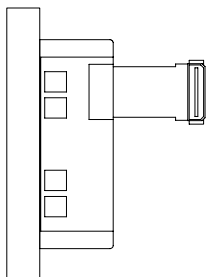


WIREBONDING CHECKLIST FOR CMS TEC HYBRIDS

Program: TEC-CH

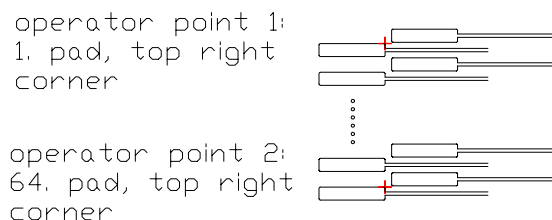
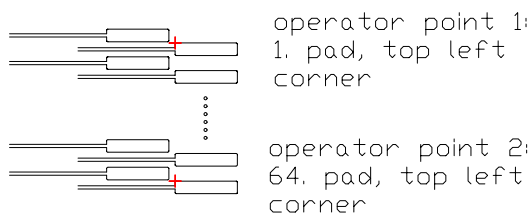
Part Orientation:



1. Pitch Adapter to Chip Bonds

Lead Reference System (L): Pitch Adapter

Die Reference System (U): Chip



First Bond: Pitch Adapter

Bond time: 20 ms

USG Current: 60 to 75mA

Force: 20

Second Bond: Chip

Bond time: 20 ms

USG Current: 48 to 55mA

Force: 35

Loop Parameters:

Shape: square

Loop height: short bonds 15 mils, long bonds 25 mils

Clear height: short bonds 25 mils, long bonds 40 mils

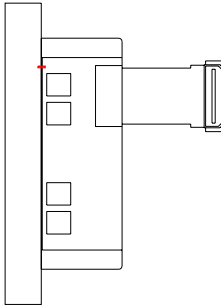
clamp close at loop

Tail Parameters:

Feed: 75

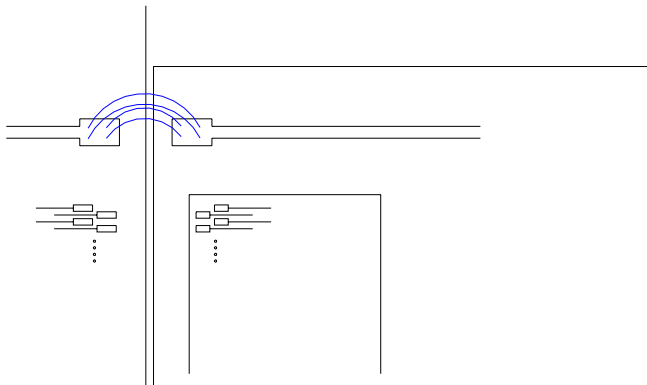
2. Hybrid Bias Bonds

Bias Bonds Location:



Pitch Adapter to Gold Pad on Hybrid:

Place 4 bonds, 2 short, 2 long



First Bond: Pitch Adapter

Bond time: 20ms

USG Current: 65 to 75mA

Force: 20

Loop Parameters:

Shape: square

Loop height: short bonds 30 mils, long bonds 40 mils

Clamp close at loop

Second Bond: Gold

Bond time: 30 to 35 ms

USG Current: 60 to 70mA

Force: 25

Tail Parameters:

Feed: 75